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Green & Intelligent Printing or Packaging Materials in Light Industry

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Deadline for manuscript submissions:

closed (20 May 2023)

Message from the Guest Editors

Dear Colleagues,

In this Special Issue, we aim to present a contemporary overview of recent developments in the fields of green printing, printed electronics and intelligent packaging. Reviews, full papers and short communications covering current trends in the expansion of polymeric material applications are all welcome.

The scope of this issue includes, but is not limited to, the following topics:

- Green preparation of environmentally friendly materials in printing and packaging;
- Recycling of waste packaging materials, such as plastic, metal, paper, etc.;
- Functional materials, including electric, optical, thermal resistance, magnetic, hydrophobic materials, etc.;
- The green fabrication technologies for preparation of smart devices;
- Reusing natural materials, such as lignin, cellulose, protein, etc.;
- Calculation and simulation technologies for material and device preparation.

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Special Issue



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Message from the Editor-in-Chief

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